

As a below named inventor(s), I (we) hereby declare that:

My (our) residence(s), post office address(es) and citizenship(s) is (are) the same as stated below next to my (our) name(s).

I (we) believe I am (we are) an original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled: **SILICON WAFER, AND MANUFACTURING METHOD AND HEAT TREATMENT METHOD OF THE SAME**

the specification of which is attached hereto unless the following box is checked:

☐ was filed on _____ as United States Application Number _____ or
PCT International Application Number _____
and was amended on _____ (if applicable).

I (we) hereby state that I (we) have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I (we) acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, §1.56.

I (we) hereby claim foreign priority benefits under Title 35, United States Code, §119(a)-(d) of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s):			Priority Claimed:	
(Number)	(Country)	(Day/Month/Year)	YES	NO

I (we) hereby claim the benefit under Title 35, United States Code, §119(e) of any United States provisional application(s) listed below:

(Application Number)

(Filing Date)

I (we) hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I (we) acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulation, §1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application.

(Application Serial No.)	(Filing date)	(STATUS-patented, pending, abandoned)

DECLARATION FOR PATENT APPLICATION

I (we) hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith and to act in accordance with the instructions from Suda Patent Office:

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I (we) hereby declare that all statements made herein of my (our) own knowledge are true, and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of sole or 1st inventor (given name, family name):		Etsuro Morita	
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Inventor's signature: Etsuro Morita Date: Sep. 7, 2000

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DECLARATION FOR PATENT APPLICATION

Full name of 4th inventor (given name, family name):		Yoshinobu Nakada	
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Inventor's signature: <u>Hisashi Furuya</u>		Date: <u>Sep. 8, 2000</u>	
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Inventor's signature: <u>Hiroshi Koya</u>		Date: <u>Sep. 11, 2000</u>	
Full name of 7th inventor (given name, family name):			
Residence:		Citizenship:	
Post Office Address:			
Inventor's signature: _____		Date: _____	
Full name of 8th inventor (given name, family name):			
Residence:		Citizenship:	
Post Office Address:			
Inventor's signature: _____		Date: _____	

DECLARATION FOR PATENT APPLICATION

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Full name of 7th inventor (given name, family name):			
Residence:		Citizenship:	
Post Office Address:			
Inventor's signature: _____		Date: _____	
Full name of 8th inventor (given name, family name):			
Residence:		Citizenship:	
Post Office Address:			
Inventor's signature: _____		Date: _____	